

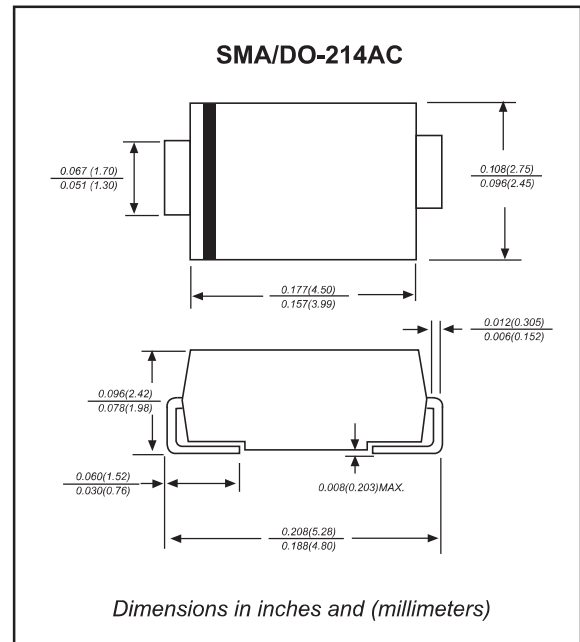
Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Ultra fast switching for high efficiency
- Low reverse leakage
- Built-in strain relief, ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed 260°C/10 seconds at terminals
- Glass passivated chip junction

Mechanical data

- **Case:** JEDEC SMA/DO-214AC molded plastic body
- **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- **Polarity:** Color band denotes cathode end
- **Mounting Position:** Any

Package outline

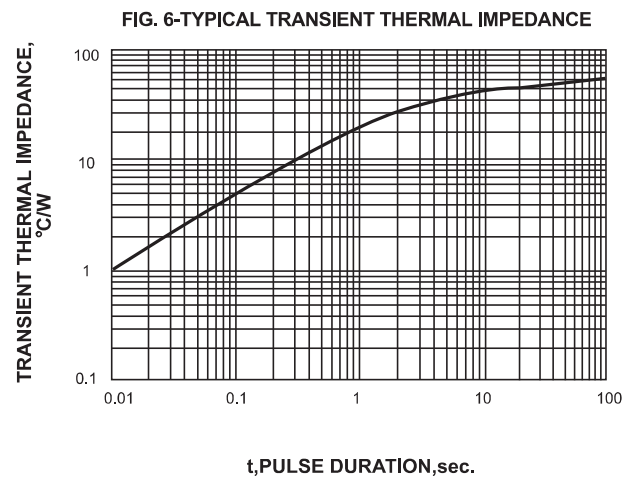
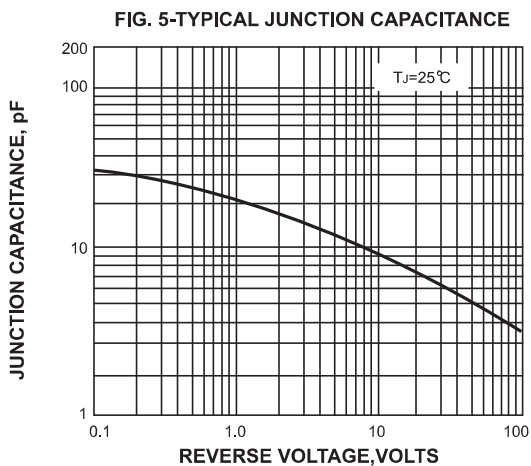
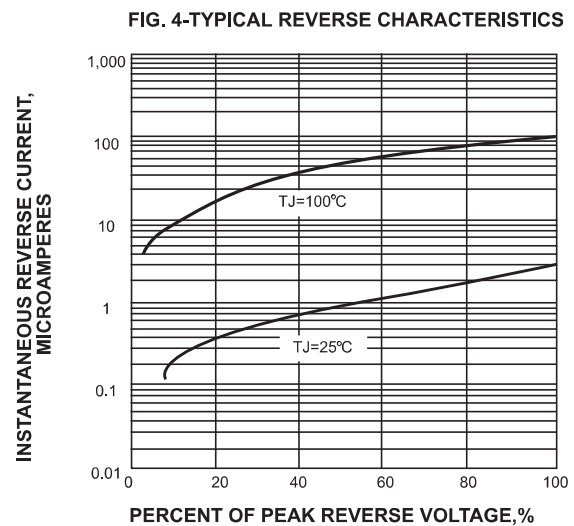
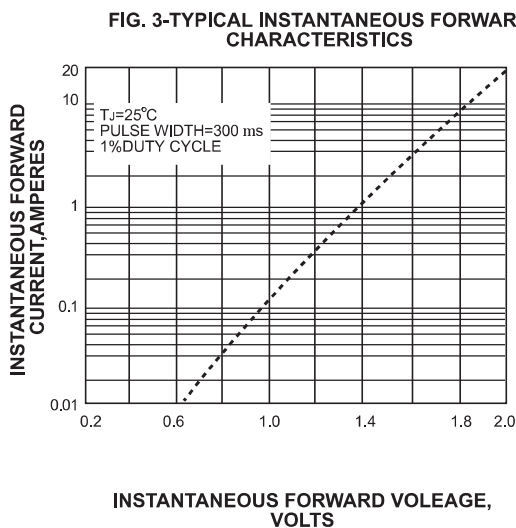
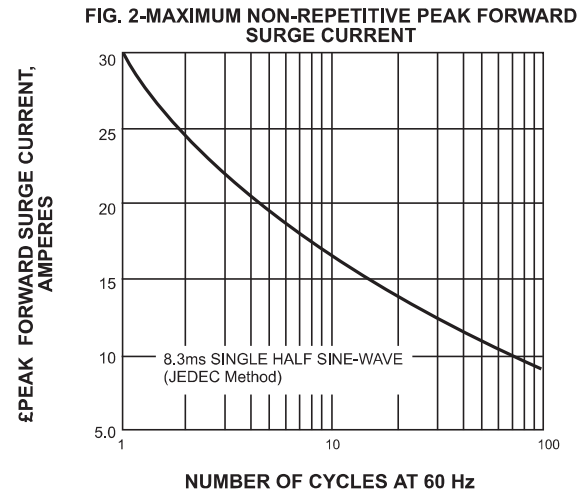
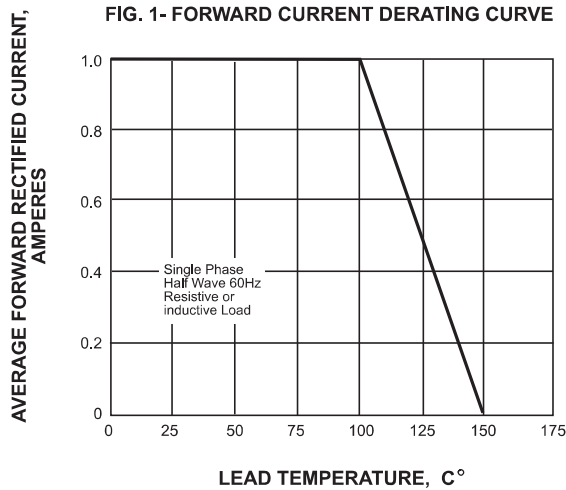


Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

	SYMBOLS	HFM108	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum DC blocking voltage	V_{DC}	1000	V
Maximum average forward rectified current at $T_L=100^\circ\text{C}$	$I_{(AV)}$	1.0	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	30.0	A
Maximum instantaneous forward voltage at 1.0A	V_F	1.7	V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$	I_R	5.0 50.0	μA
Maximum reverse recovery time (NOTE 1)	t_{rr}	75	ns
Typical junction capacitance (NOTE 2)	C_J	15.0	pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	75.0	$^\circ\text{C/W}$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Note: 1.Reverse recovery condition $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{rr}=0.25\text{A}$
 2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 3.P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

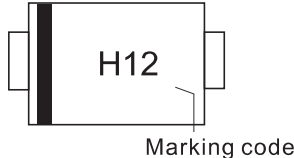
Rating and characteristic curves



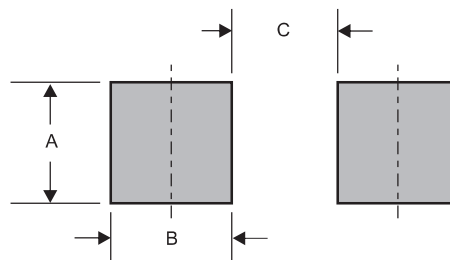
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code	Example
HFM108	H12	

Suggested solder pad layout

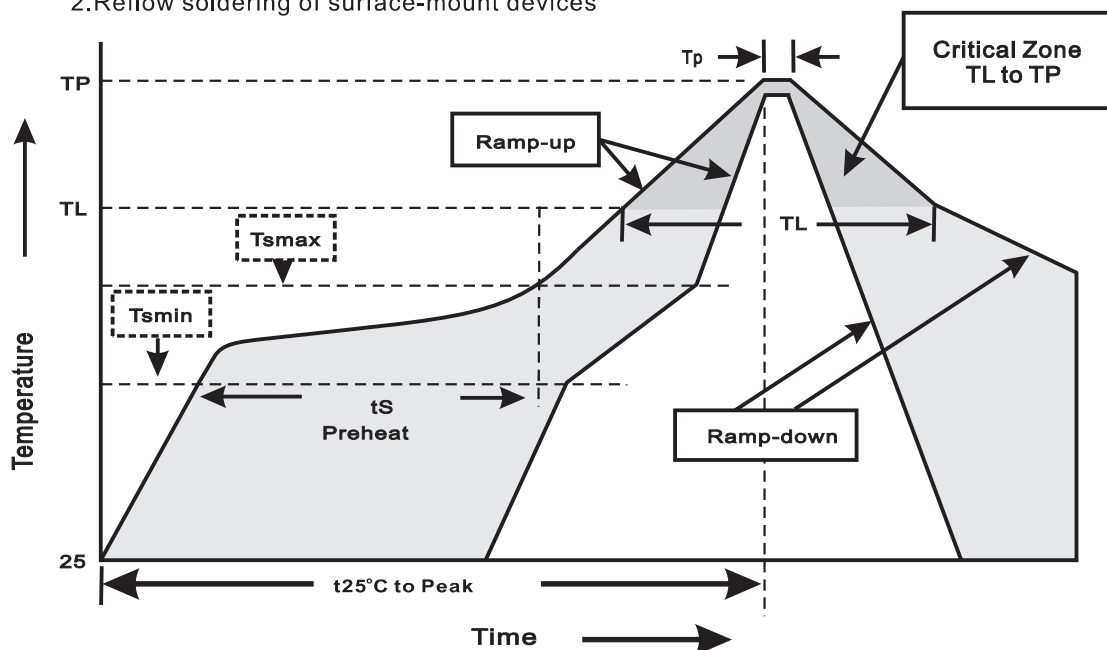


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMA	0.110 (2.80)	0.063 (1.60)	0.087 (2.20)

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	$<3^{\circ}\text{C}/\text{sec}$
Preheat -Temperature Min(T_{min}) -Temperature Max(T_{max}) -Time(min to max)(t_s)	150°C 200°C $60\sim 120\text{sec}$
T_{max} to T_L -Ramp-upRate	$<3^{\circ}\text{C}/\text{sec}$
Time maintained above: -Temperature(T_L) -Time(t_L)	217°C $60\sim 260\text{sec}$
Peak Temperature(T_P)	$255^{\circ}\text{C}-0/+5^{\circ}\text{C}$
Time within 5°C of actual Peak Temperature(t_P)	$10\sim 30\text{sec}$
Ramp-down Rate	$<6^{\circ}\text{C}/\text{sec}$
Time 25°C to Peak Temperature	$<6\text{minutes}$